

Product Change Notice

PCN Number: 12-0522-04 Issue Date: 05-06-2013

Exar Corporation

www.exar.com | Support: customersupport@exar.com

PRODUCTS AFFECTED:	SP508CF-L, SP508EF-L						
CHANGE CATEGORY:							
Material					Package		
Design	□ Datasheet			t	Packing/Shipping		
Other (specify)							
DESCRIPTION OF CHANGE:							
Change in wafer fabrication foundry and part numbers.							
Qualification of an alternate qualified wafer foundry, Silan, in addition to the current wafer foundry, Episil Technologies.							
FROM:				TO:			
Part Numbers:				Part Numbers:			
• SP508CF-L				• SP508ECF-L			
• SP508EF-L				SP508EEF-L			
Datasheet limits for the following parameters are being changed from:				Datasheet limits for the following parameters are being changed to:			
PARAMETER	OLD SPEC		UNIT	PARAMETER	NEW SPEC		UNIT
	Low Limit	High Limit			Low Limit	High Limit	
V.10 Driver Transition Time	N/A	200	Ns	V.10 Driver Transition Time	N/A	500	Ns
V.10 Receiver Propagation Delay TpH-L and TPL-H	N/A	60	ns	V.10 Receiver Propagation Delay TpH-L and TPL-H	N/A	500	ns
V.35 Driver Channel to Channel Skew	Typical = 5nS		ns	V.35 Driver Channel to Channel Skew	Typical = 2ns		ns
Icc (Shut Down Mode)	Typical = 1uA		uA	Icc (Shut Down Mode)	Typical = 200uA		uA
IMPACT OF CHANGE: None expected for known customer applications.							

TARGET IMPLEMENTATION DATE: 29-APR-2013

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data

PROPRIETARY INFORMATION

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